

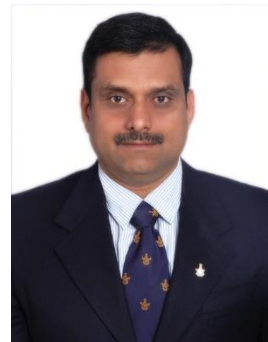


VLSI Design : 2022-23

Lecture 4

CMOS Inverter Static Characteristics

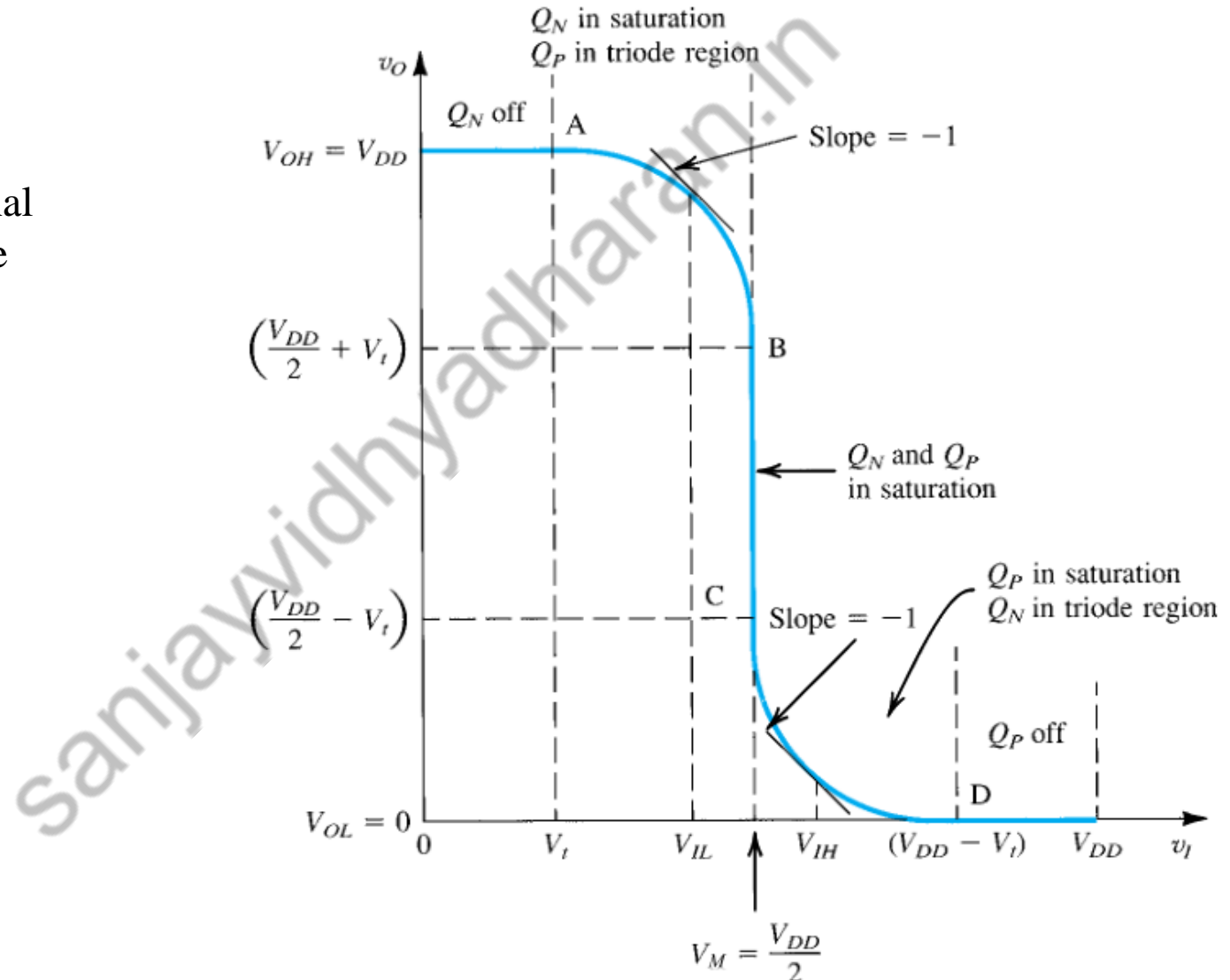
By Dr. Sanjay Vidhyadharan



Noise Margin

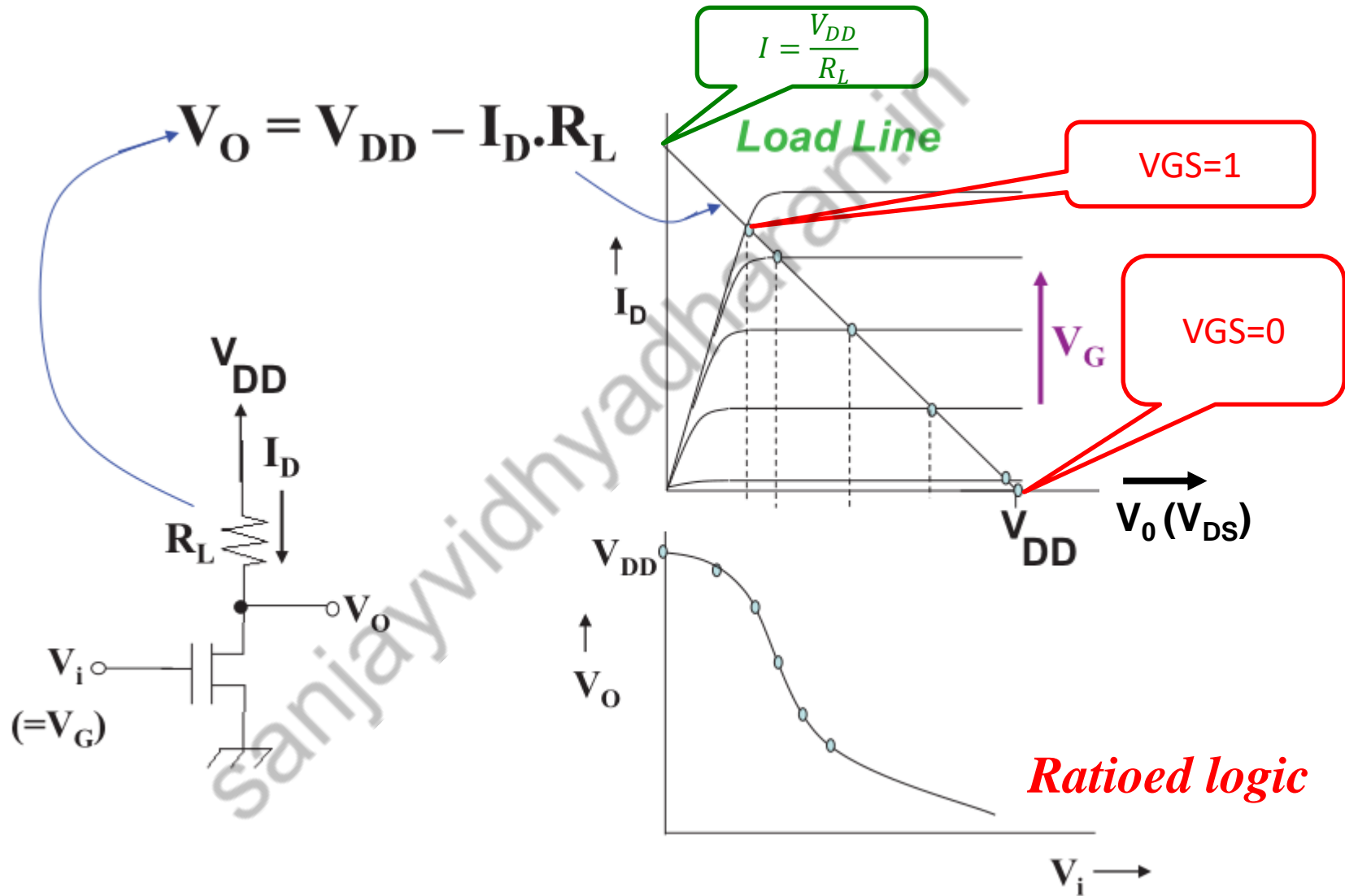
For MOSFET Inverters

V_{IH} , V_{IL} are operational points of inverter where $dV_{out}/dV_{in} = -1$



8/13/2022

Resistive Load Inverter



MOSFET Current Equations

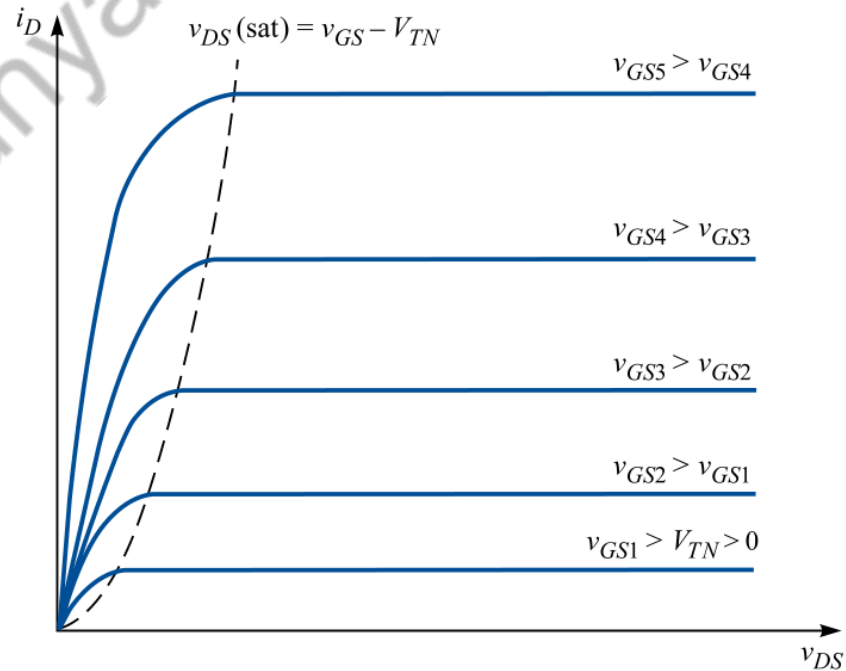
1. $I_D = \frac{k'_n W V_{ov} V_{DS}}{L}$ Small V_{DS}

2. $I_D = \frac{k'_n W (V_{ov} - \frac{V_{DS}}{2}) V_{DS}}{L}$ As V_{DS} Increases ($V_{DS} < V_{GS} - V_T$) : Linear Region

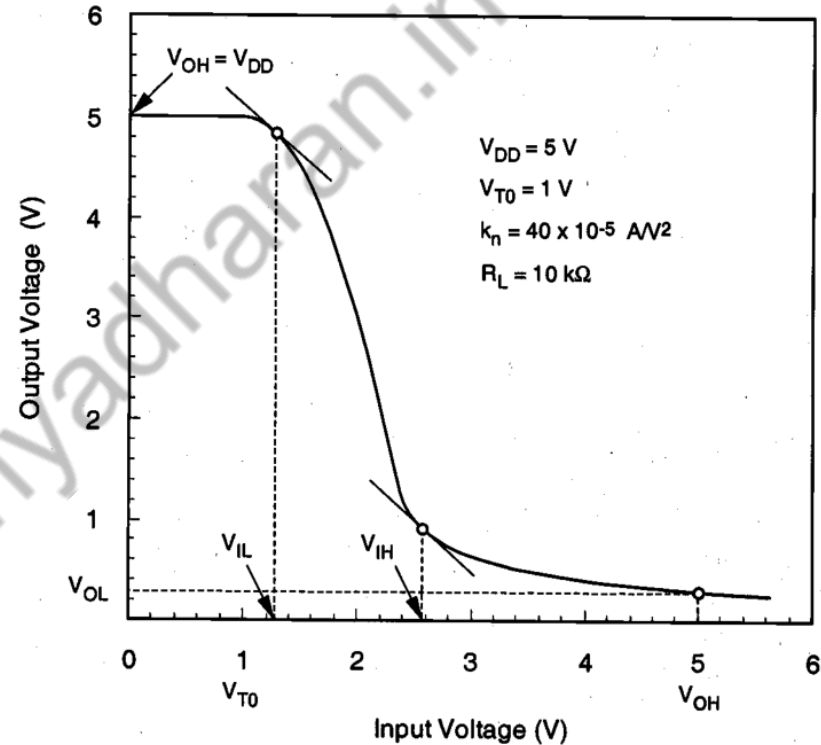
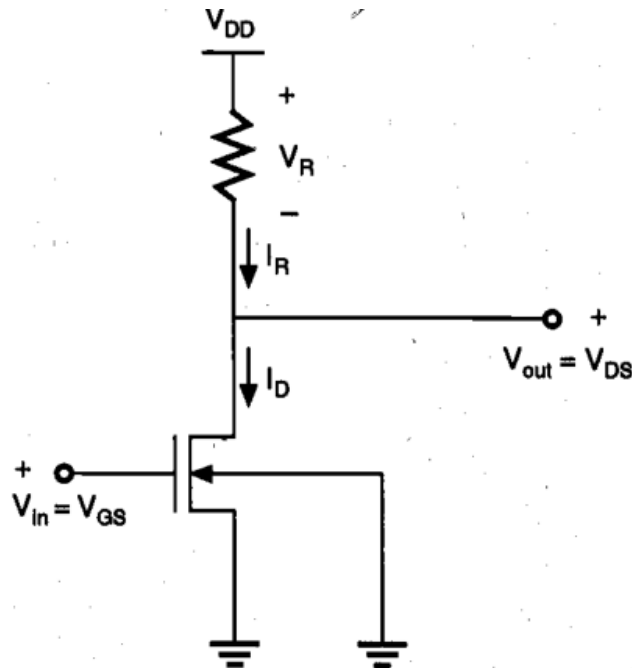
3. $I_D = \frac{k'_n W (V_{GS} - V_T)^2}{2L}$ $V_{DS} \geq V_{GS} - V_T$: Saturation Region

$$K_n = \frac{k'_n W}{L}$$

$$I_D = \frac{K_n (V_{GS} - V_T)^2}{2}$$



Resistive Load Inverter

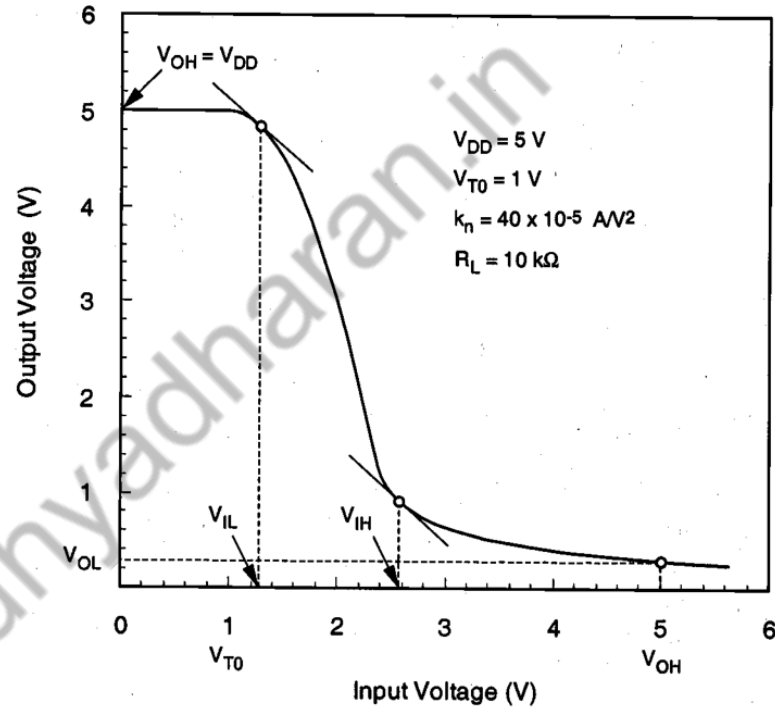
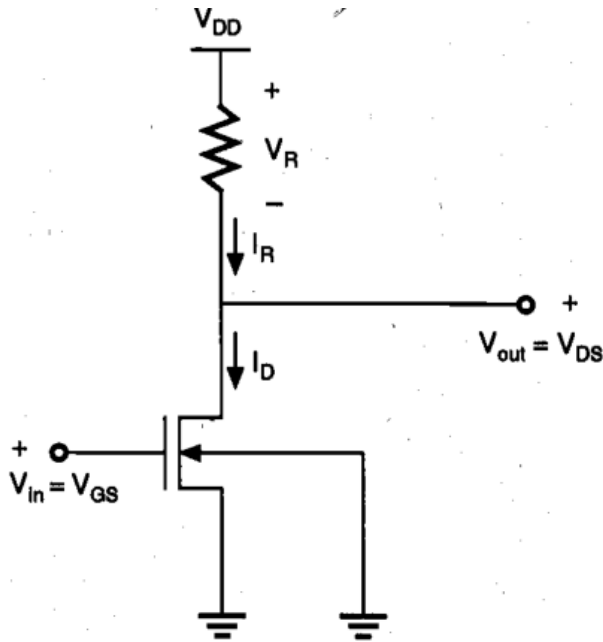


Calculation of V_{OH}

$$V_{Out} = V_{DD} - R_L I_R$$

$$V_{OH} = V_{DD}$$

Resistive Load Inverter



Calculation of V_{OL}

$$I_R = \frac{V_{DD} - V_{out}}{R_L}$$

$$k = k' \cdot \frac{W}{L}$$

$$k' = \mu_n \cdot C_{ox}$$

$$\frac{V_{DD} - V_{OL}}{R_L} = \frac{k_n}{2} \cdot [2 \cdot (V_{DD} - V_{T0}) \cdot V_{OL} - V_{OL}^2]$$

$$V_{OL} = V_{DD} - V_{T0} + \frac{1}{k_n R_L} - \sqrt{\left(V_{DD} - V_{T0} + \frac{1}{k_n R_L} \right)^2 - \frac{2 V_{DD}}{k_n R_L}}$$

Ratioed logic

Resistive Load Inverter

Calculation of V_{IL}

$$\frac{V_{DD} - V_{out}}{R_L} = \frac{k_n}{2} \cdot (V_{in} - V_{T0})^2$$

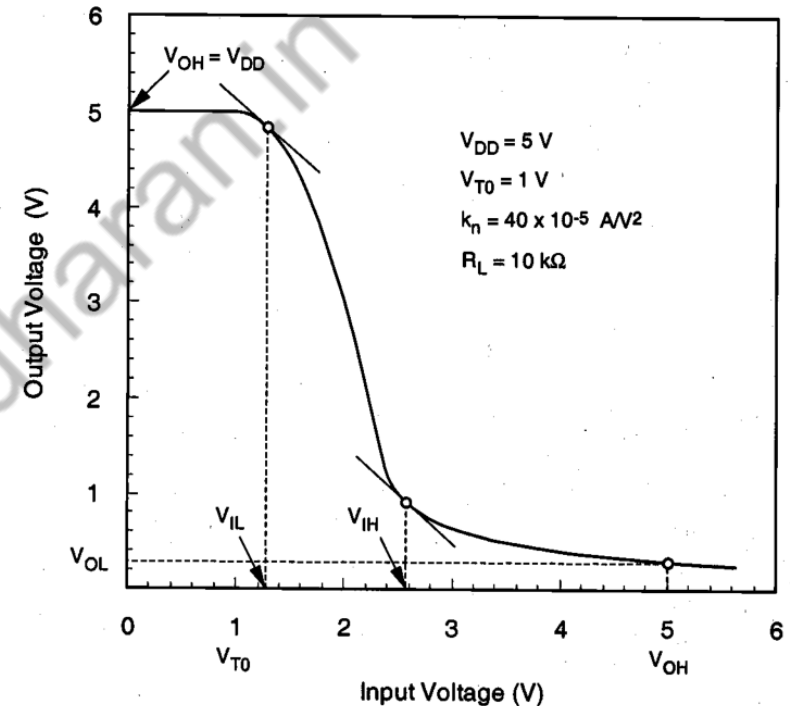
Differentiating both sides with respect to V_{in}

$$-\frac{1}{R_L} \cdot \frac{dV_{out}}{dV_{in}} = k_n \cdot (V_{in} - V_{T0})$$

$$-\frac{1}{R_L} \cdot (-1) = k_n \cdot (V_{IL} - V_{T0}) \quad \left[\frac{dV_O}{dV_i} = -1 \right]$$

$$V_{IL} = V_{T0} + \frac{1}{k_n R_L}$$

$$\begin{aligned} V_{out}(V_{in} = V_{IL}) &= V_{DD} - \frac{k_n R_L}{2} \cdot \left(V_{T0} + \frac{1}{k_n R_L} - V_{T0} \right)^2 \\ &= V_{DD} - \frac{1}{2 k_n R_L} \end{aligned}$$



Resistive Load Inverter

Calculation of V_{IH}

$$\frac{V_{DD} - V_{out}}{R_L} = \frac{k_n}{2} \cdot [2 \cdot (V_{in} - V_{T0}) \cdot V_{out} - V_{out}^2]$$

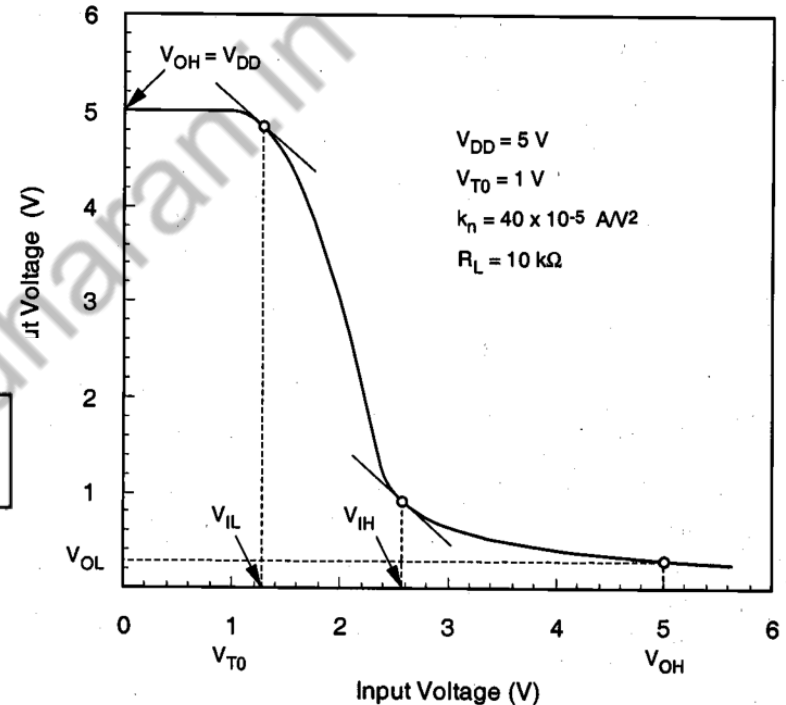
Differentiating both sides with respect to V_{in}

$$-\frac{1}{R_L} \cdot \frac{dV_{out}}{dV_{in}} = \frac{k_n}{2} \cdot \left[2 \cdot (V_{in} - V_{T0}) \cdot \frac{dV_{out}}{dV_{in}} + 2V_{out} - 2V_{out} \cdot \frac{dV_{out}}{dV_{in}} \right]$$

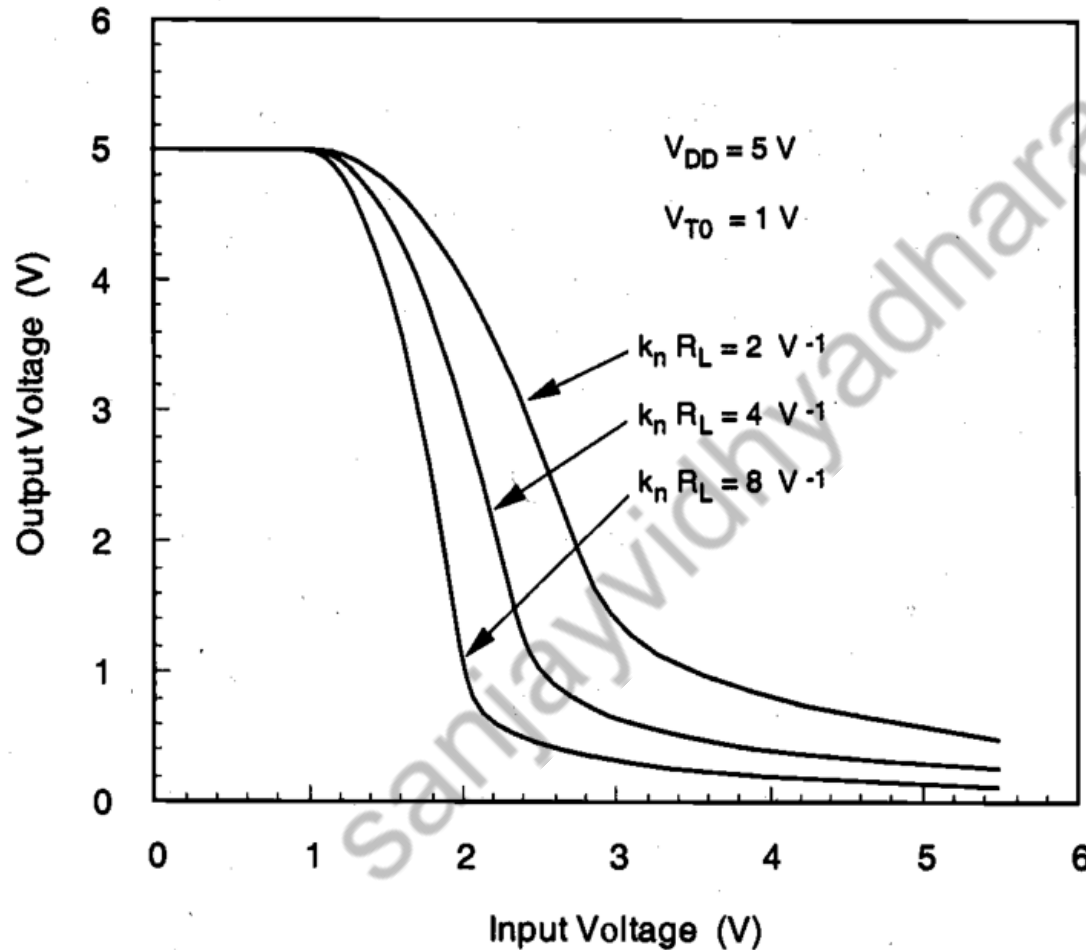
$$-\frac{1}{R_L} \cdot (-1) = k_n \cdot [(V_{IH} - V_{T0}) \cdot (-1) + 2V_{out}] \quad \left[\frac{dV_{out}}{dV_{in}} = -1 \right]$$

$$V_{IH} = V_{T0} + \sqrt{\frac{8}{3} \cdot \frac{V_{DD}}{k_n R_L} - \frac{1}{k_n R_L}}$$

$$V_{out}(V_{in} = V_{IH}) = \sqrt{\frac{2}{3} \cdot \frac{V_{DD}}{k_n R_L}}$$



Resistive Load Inverter

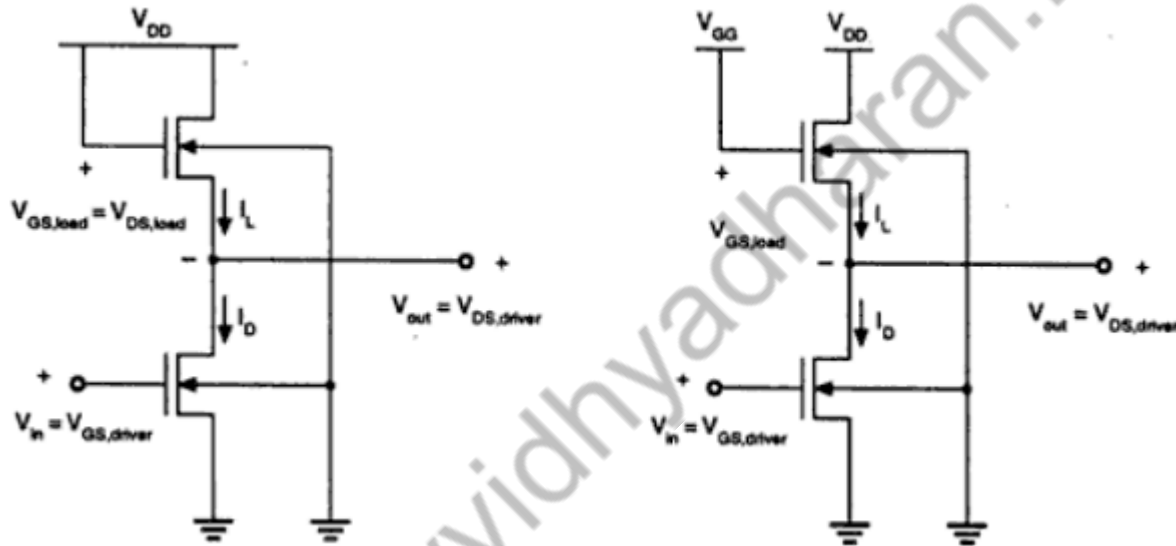


$$\text{Gain} = \partial V_O / \partial V_i$$

$$V_O = V_{DD} - I_D \cdot R_L$$

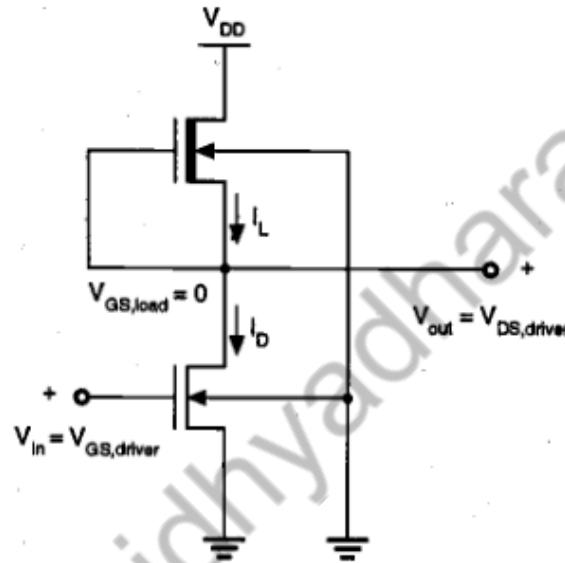
$$I_D = \frac{K_n (V_{GS} - V_T)^2}{2}$$

Enhancement-Load nMOS Inverter



- Relatively simple fabrication process
- V_{OH} level is limited to $V_{DD} - V_T$
- Two separate power supply
- $V_{OH} = V_{DD}$
- High Static Power

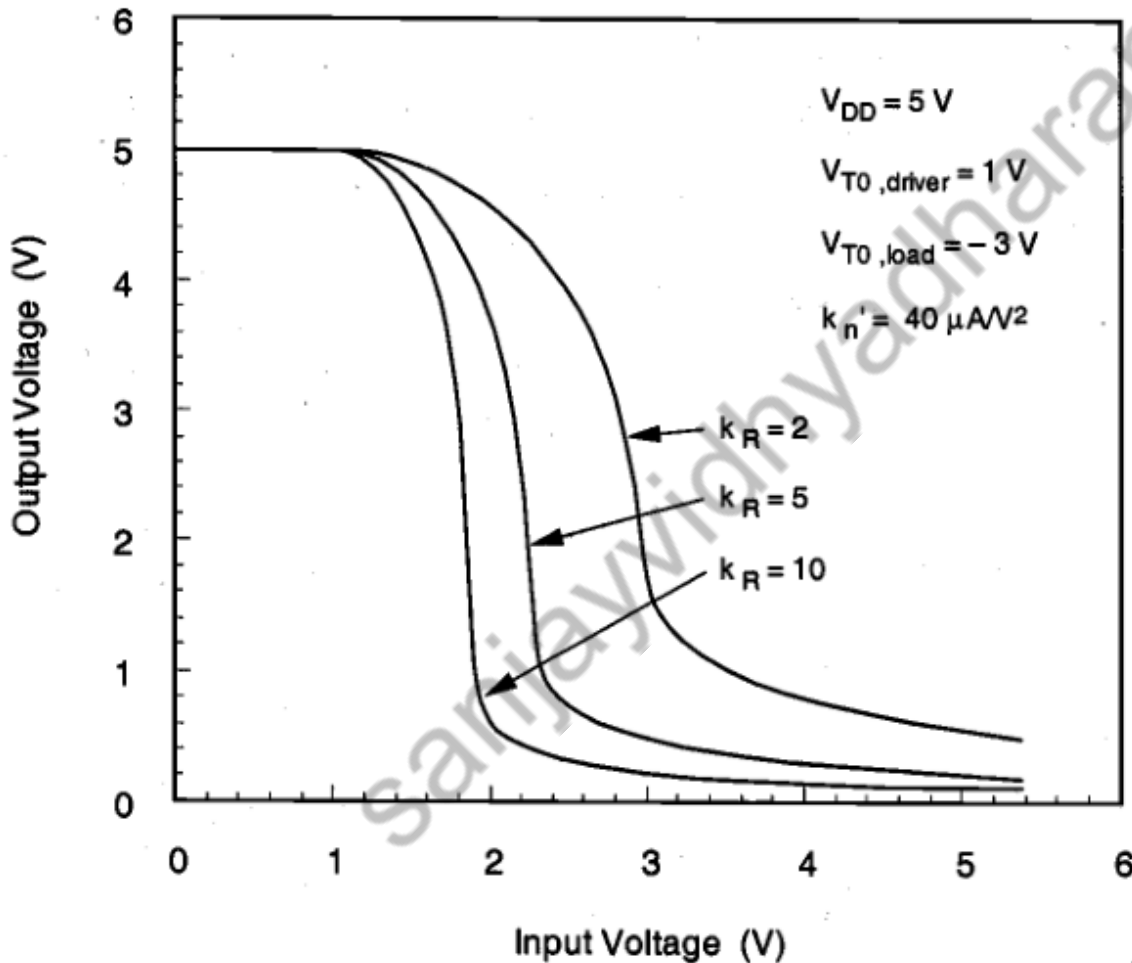
Depletion-Load nMOS Inverter



Depletion-type nMOS load is more complicated & requires additional processing steps

- $V_{OH} = V_{DD}$
- Single power supply

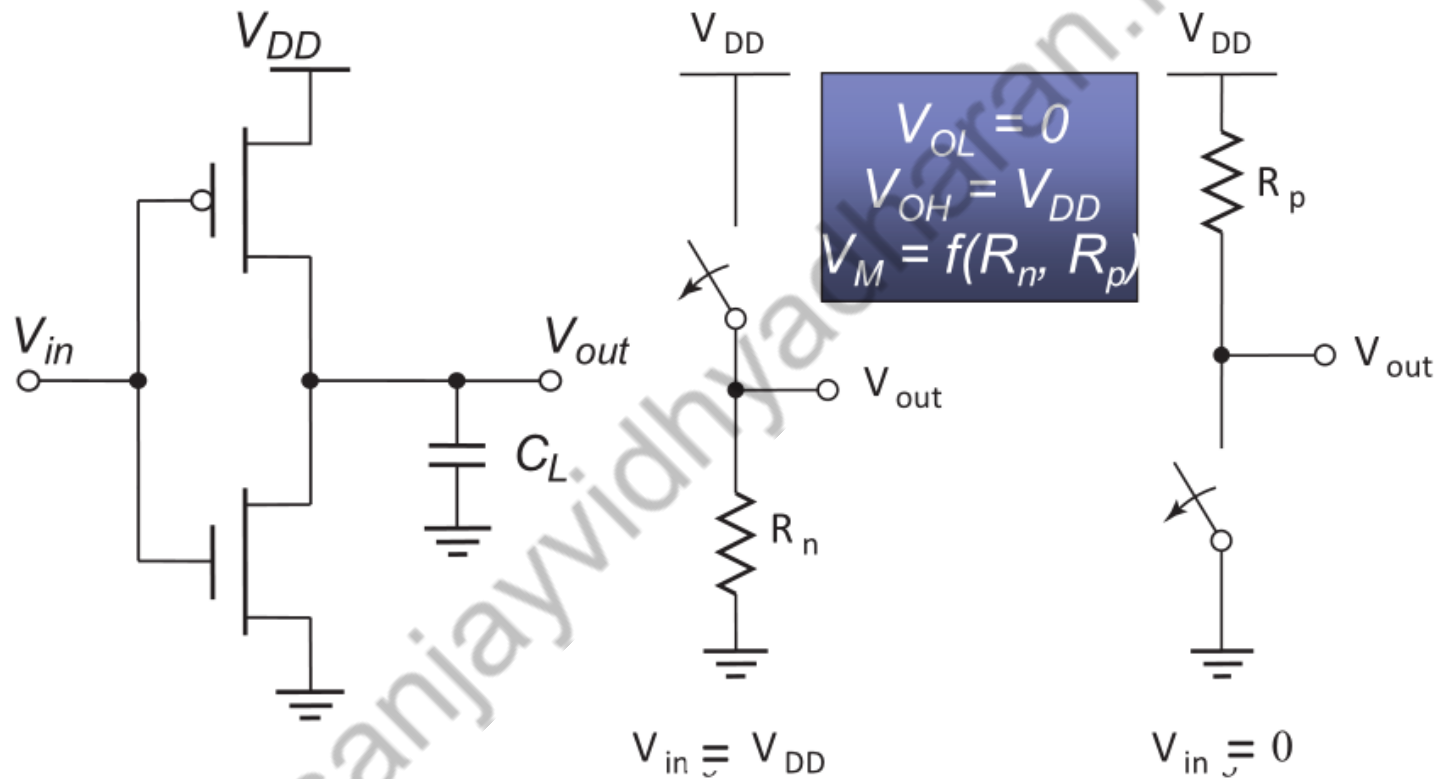
Depletion-Load nMOS Inverter



$$k_R = (k_{\text{driver}} / k_{\text{load}}).$$

The CMOS Inverter

It is the nucleus of all digital designs

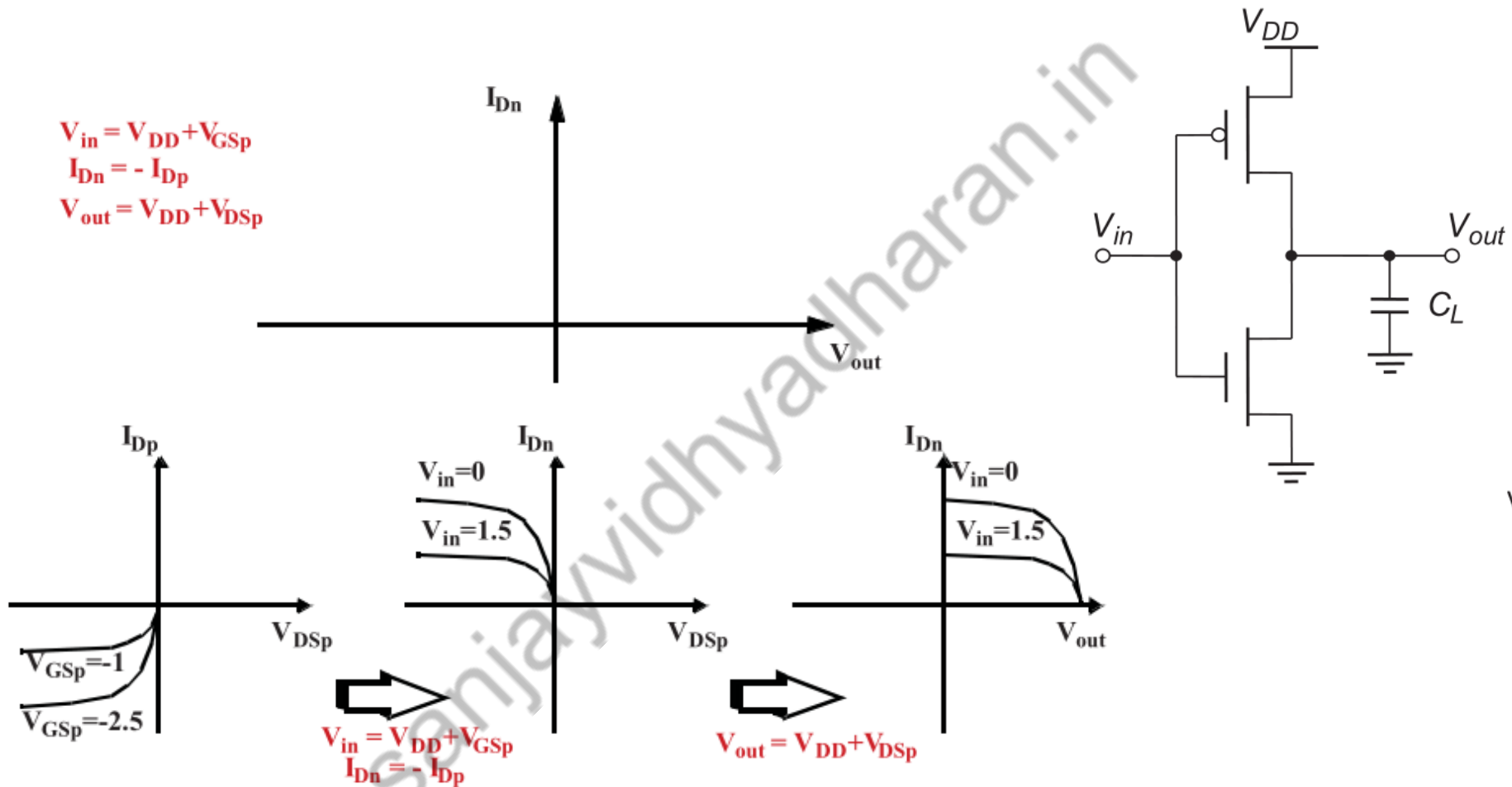


Assumed infinite off-resistance for $V_{GS} < V_{TH}$ and finite on-resistance for $V_{GS} > V_{TH}$

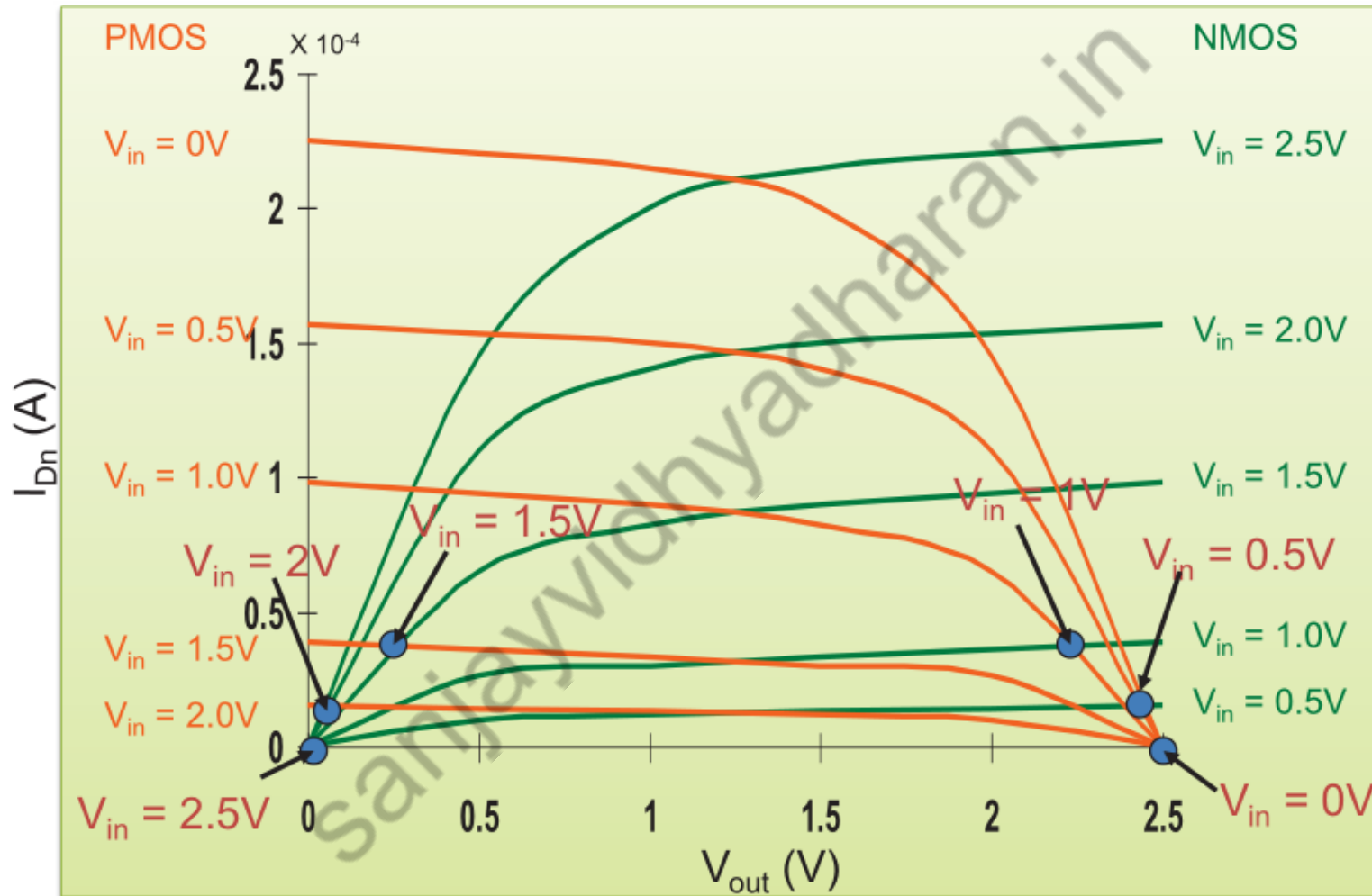
Important properties of static CMOS

- Rail-to-Rail O/p : The high and low output levels equal V_{DD} and GND, respectively. This results in high noise margins.
- **Ratioless:** The logic levels are not dependent upon the relative device sizes, so that the transistors can be minimum size.
- In steady state, there always exists a path with finite resistance between the output and either V_{DD} or GND.
- The input resistance of the CMOS inverter is extremely high, the steady-state input current is nearly zero.
- A single inverter can theoretically drive an infinite number of gates (or have an infinite fan-out) and still be functionally operational. However, increasing the fan-out also increases the propagation delay.
- No direct path exists between the supply and ground rails under steady-state operating conditions (this is, when the input and outputs remain constant). The absence of current flow (ignoring leakage currents) means that the gate does not consume any static power.

The PMOS Load Line

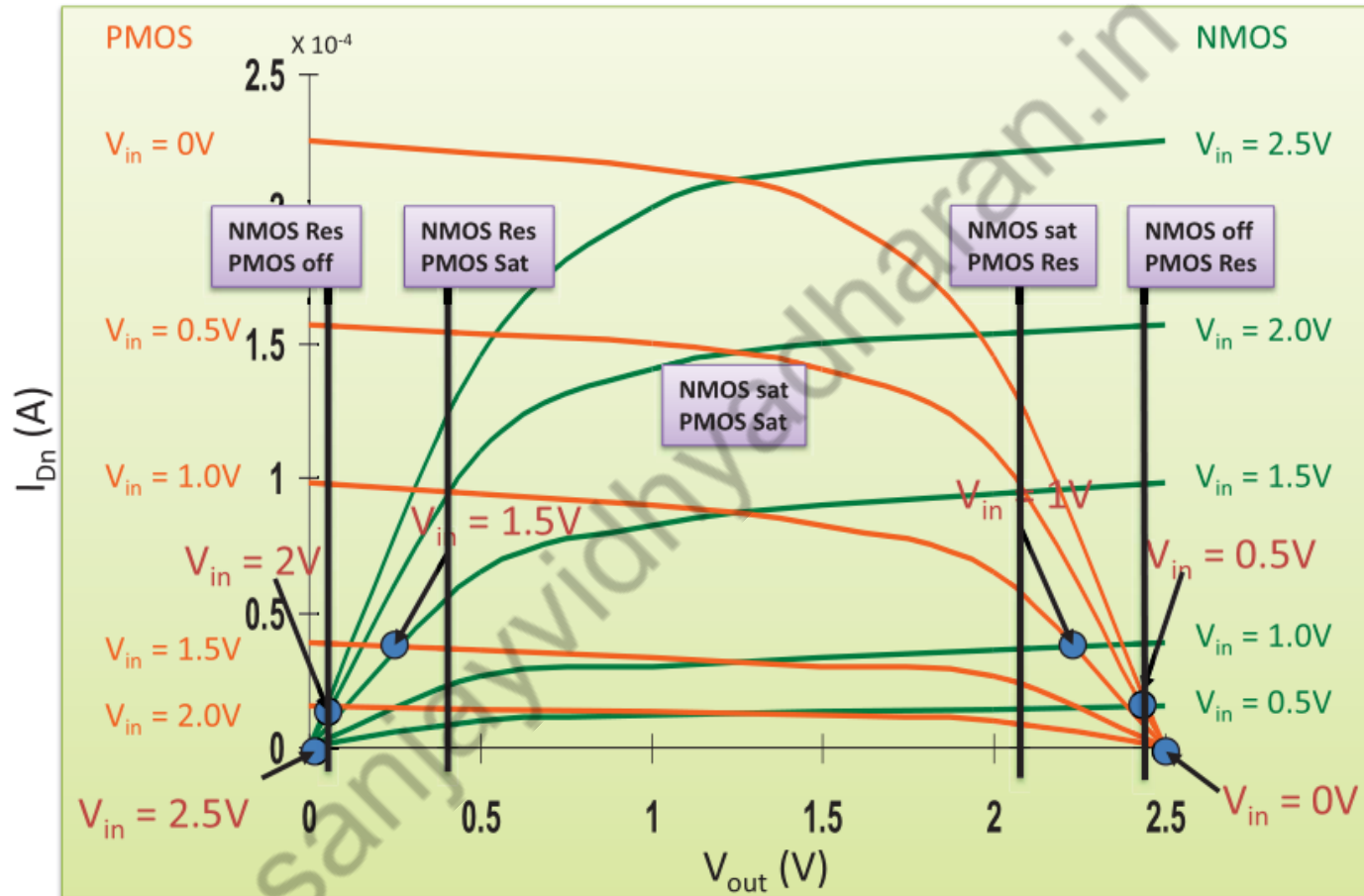


CMOS Inverter Load Characteristic



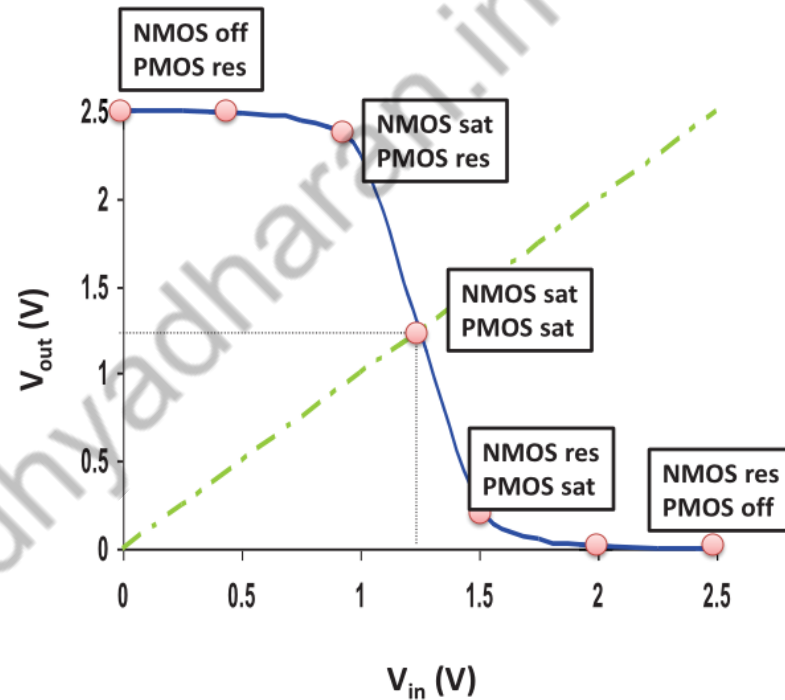
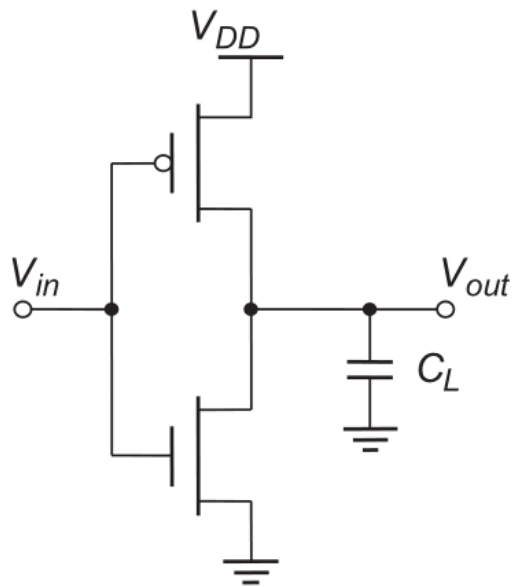
0.25 μ m, $W/L_n = 1.5$, $W/L_p = 4.5$, $V_{DD} = 2.5$ V, $V_{Tn} = 0.4$ V, $V_{Tp} = -0.4$ V

CMOS Inverter Load Characteristic



$0.25\mu\text{m}$, $W/L_n = 1.5$, $W/L_p = 4.5$, $V_{DD} = 2.5\text{V}$, $V_{Tn} = 0.4\text{V}$, $V_{Tp} = -0.4\text{V}$

CMOS Inverter VTC



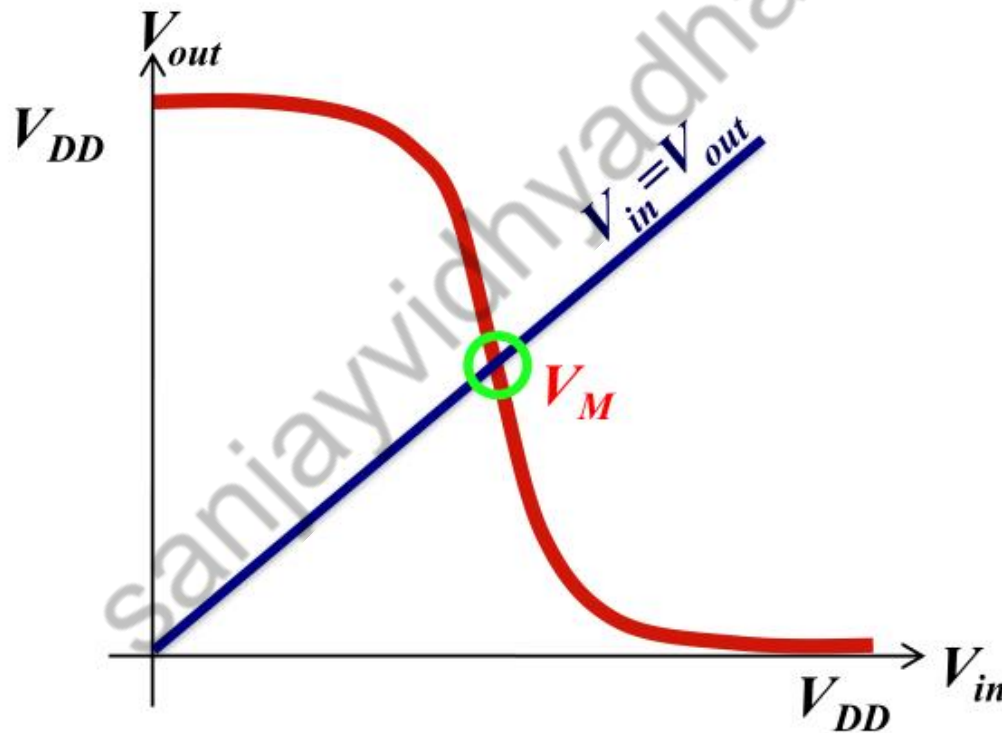
The VTC of the inverter hence exhibits a very narrow transition zone. This results from the high gain during the switching transient, when both NMOS and PMOS are simultaneously on, and in saturation. In that operation region, a small change in the input voltage results in a large output variation.

CMOS Inverter Switching Threshold

The Switching Threshold, V_M , is the point where $V_{in} = V_{out}$.

This can be calculated:

» Graphically, at the intersection of the VTC with $V_{in} = V_{out}$



CMOS Inverter Switching Threshold

□ Let's analytically compute V_M .

» Remember, the saturation current for a MOSFET is given by:

$$I_{DS} = \frac{k}{2} (V_{GS} - V_T)^2 (1 + \lambda V_{DS})$$

» Lets assume $\lambda=0$ and we'll equate the two currents:

$$I_D = \frac{k_n}{2} (V_{GSn} - V_{Tn})^2 = \frac{k_p}{2} (V_{SGp} - V_{Tp})^2$$

» Now we'll substitute:

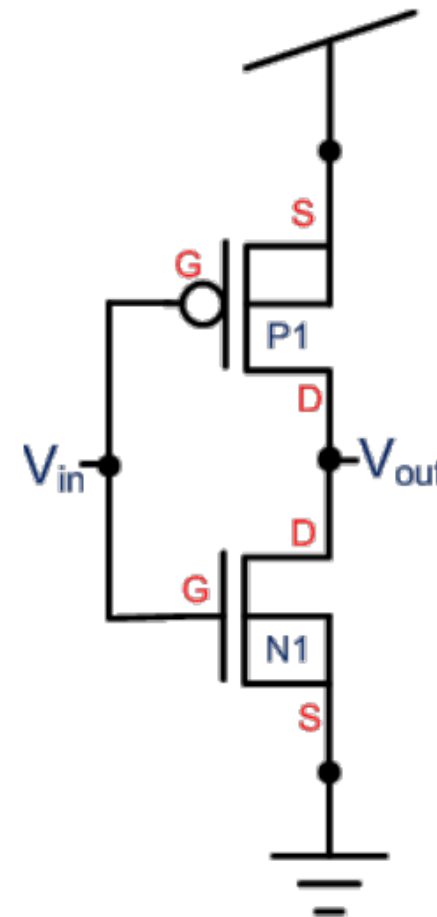
$$V_{GSn} = V_{in} = V_M$$

$$V_{SGp} = V_{DD} - V_{in} = V_{DD} - V_M$$

» And we'll arrive at:

$$V_M = \frac{V_{Tn} + r(V_{DD} - V_{Tp})}{1 + r}$$

$$r \triangleq \sqrt{\frac{k_p}{k_n}}$$



CMOS Inverter Switching Threshold

- A symmetric VTC ($V_M = V_{DD}/2$) is often desired. In this case:

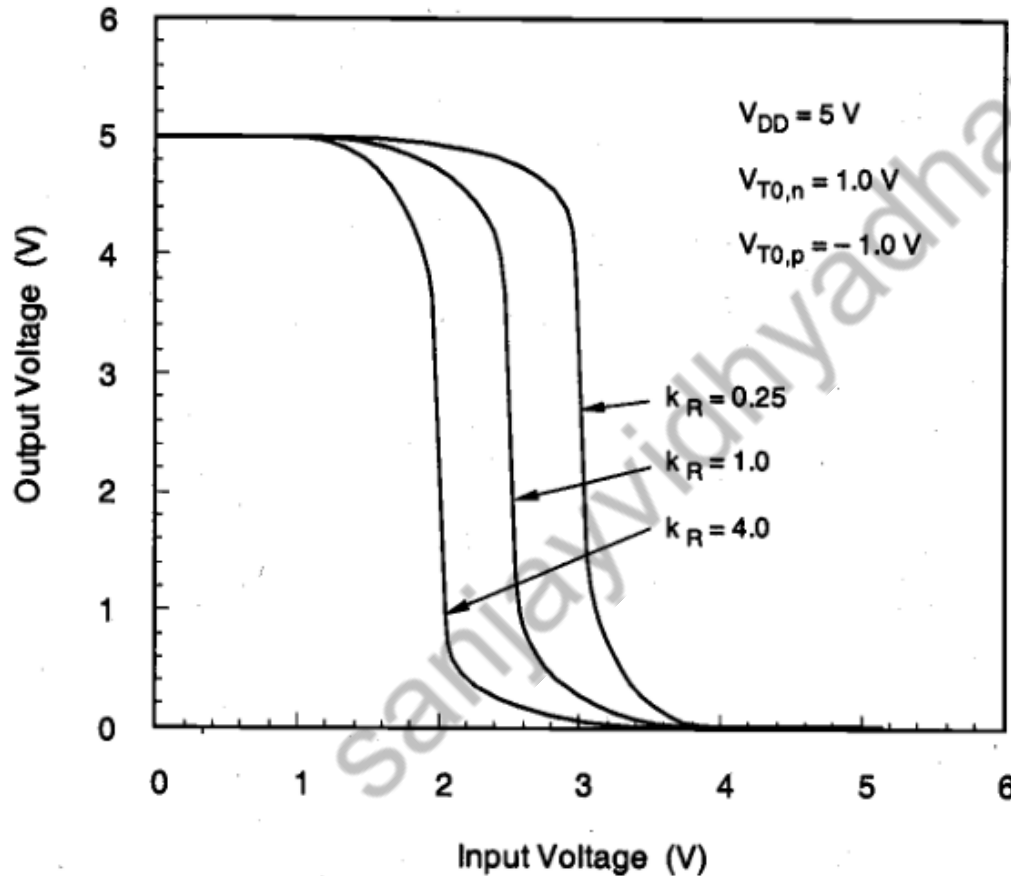
$$V_M = \frac{V_{DD}}{2} = \frac{V_{Tn} + r(V_{DD} - V_{Tp})}{1+r} \longrightarrow \left(\frac{W}{L}\right)_p = \frac{\mu_n}{\mu_p} \left(\frac{W}{L}\right)_n$$

- Generally, the same length (L_{min}) is taken for all transistors in digital circuits, and so for a symmetric VTC :

$$\frac{\left(\frac{W}{L}\right)_n}{\left(\frac{W}{L}\right)_p} = \frac{\mu_p}{\mu_n} \approx \frac{230 \text{ cm}^2/\text{V}\cdot\text{s}}{580 \text{ cm}^2/\text{V}\cdot\text{s}}$$

$$\left(\frac{W}{L}\right)_p \approx 2.5 \left(\frac{W}{L}\right)_n$$

CMOS Inverter Switching Threshold



$$k_R = \frac{k_n}{k_p}$$

CMOS Inverter Switching Threshold

For Short Channel Devices

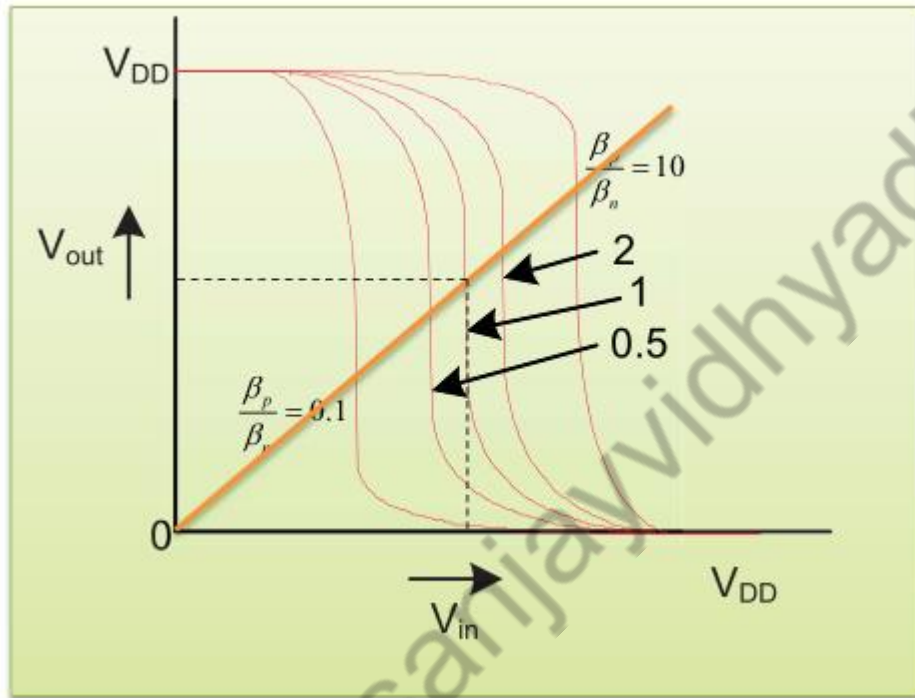
$$k_n V_{DSATn} \left(V_M - V_{Tn} - \frac{V_{DSATn}}{2} \right) + k_p V_{DSATp} \left(V_M - V_{DD} - V_{Tp} - \frac{V_{DSATp}}{2} \right) = 0$$

$$V_M = \frac{\left(V_{Tn} + \frac{V_{DSATn}}{2} \right) + r \left(V_{DD} + V_{Tp} + \frac{V_{DSATp}}{2} \right)}{1 + r}$$

$$r = \frac{k_p V_{DSATp}}{k_n V_{DSATn}} = \frac{v_{satp} W_p}{v_{satn} W_n} \quad r = \frac{\beta_p V_{DSATp}}{\beta_n V_{DSATn}} = \frac{v_{satp} W_p}{v_{satn} W_n} \quad r \approx \beta_p / \beta_n$$

$$v_{sat} = \begin{cases} 8 \times 10^6 \text{ cm/s} & \text{for electrons in Si} \\ 6 \times 10^6 \text{ cm/s} & \text{for holes in Si} \end{cases}$$

CMOS Inverter Switching Threshold



$$r \approx \beta_p / \beta_n$$

If $\beta_p / \beta_n \neq 1$

Then its called **skewed inverter**

HI-Skewed $\beta_p / \beta_n > 1$

LO-Skewed $\beta_p / \beta_n < 1$

CMOS Inverter Switching Threshold

Increasing the width of the PMOS moves V_M towards V_{DD}

Increasing the width of the NMOS moves V_M towards GND

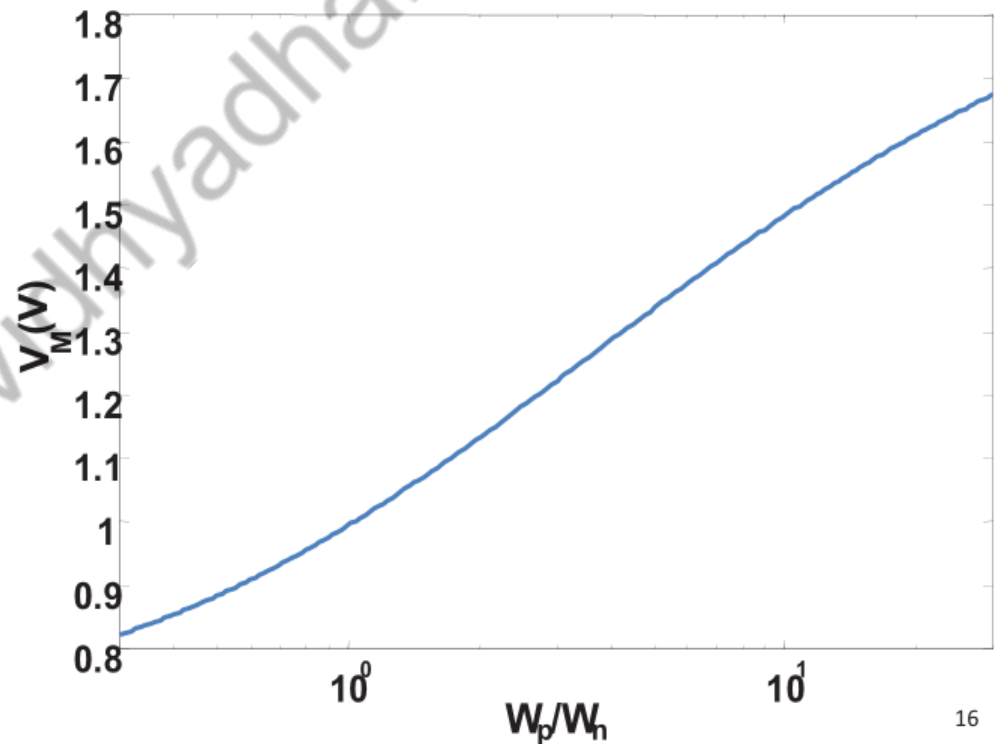
β \rightarrow V_M (250 nm $V_{DD} = 2.5$ V)

3 \rightarrow 1.22 V

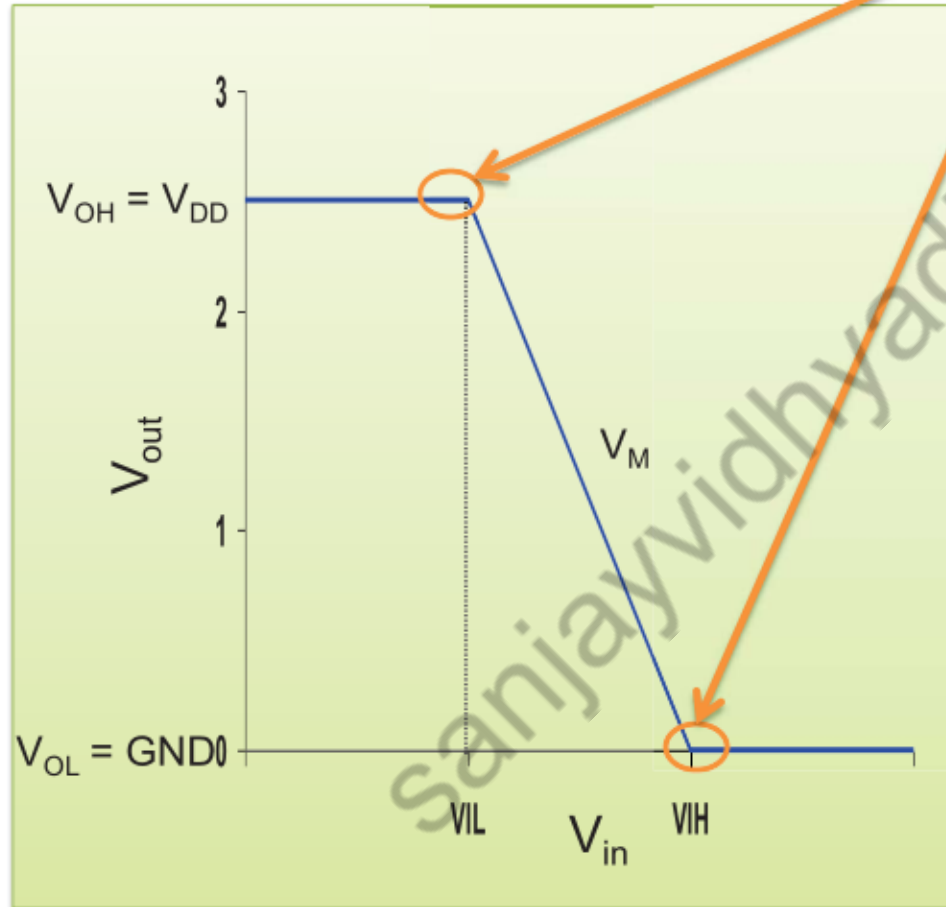
2.5 \rightarrow 1.18 V

2 \rightarrow 1.13 V

Since it not making much difference



Noise Margin



$$dV_{out}/dV_{in} = -1$$

$$NM_H = V_{DD} - V_{IH}$$

$$NM_L = V_{IL} - GND$$

Assuming gain 'g' in transition region

Find V_{IH} and V_{IL}

Noise Margin

For V_{IL}

$$I_D = \frac{k_n}{2} (V_{gs,n} - V_{T0,n})^2 = \frac{k_n}{2} (V_{in} - V_{T0,n})^2 \quad \dots \text{nMOS}$$

$$I_L = \frac{k_p}{2} [2(V_{gs,p} - V_{T0,p})V_{ds,p} - V_{ds,p}^2]$$

$$I_L = \frac{k_p}{2} [2(V_{in} - V_{DD} - V_{T0,p})(V_{out} - V_{DD}) - (V_{out} - V_{DD})^2] \quad \dots \text{pMOS}$$

$$I_L = I_D$$

$$\frac{k_n}{2} (V_{in} - V_{T0,n})^2 = \frac{k_p}{2} [2(V_{in} - V_{DD} - V_{T0,p})(V_{out} - V_{DD}) - (V_{out} - V_{DD})^2]$$

$$V_{in} = V_{IL} \quad \& \quad \frac{dV_{out}}{dV_{in}} = -1$$

$$k_n (V_{IL} - V_{T0,n}) = k_p \left[(V_{in} - V_{DD} - V_{T0,p}) \frac{dV_{out}}{dV_{in}} + (V_{out} - V_{DD}) - (V_{out} - V_{DD}) \frac{dV_{out}}{dV_{in}} \right]$$

$$k_n (V_{IL} - V_{T0,n}) = k_p \left[(V_{in} - V_{DD} - V_{T0,p})(-1) + (V_{out} - V_{DD}) - (V_{out} - V_{DD})(-1) \right]$$

$$V_{IL} = \frac{2V_{out} + V_{T0,p} - V_{DD} + K_R V_{T0,n}}{1 + K_R}$$

Noise Margin

For V_{IH}

$$V_{in} = V_{IH} \quad \& \quad \frac{dV_{out}}{dV_{in}} = -1$$

$$k_p(V_{in} - V_{DD} - V_{T0,p}) = k_n \left[(V_{in} - V_{T0,n}) \frac{dV_{out}}{dV_{in}} + (V_{out}) - (V_{out}) \frac{dV_{out}}{dV_{in}} \right]$$

$$k_p(V_{IH} - V_{DD} - V_{T0,p}) = k_n \left[(V_{IH} - V_{T0,n})(-1) + (V_{out}) - (V_{out})(-1) \right]$$

$$k_p(V_{IH} - V_{DD} - V_{T0,p}) = k_n(V_{T0,n} - V_{IH} + 2V_{out})$$

$$\frac{k_n}{k_p}(V_{T0,n} + 2V_{out}) = \frac{k_n}{k_p}V_{IH} + V_{IH} - V_{DD} - V_{T0,p}$$

$$\frac{k_n}{k_p}(V_{T0,n} + 2V_{out}) = \left(1 + \frac{k_n}{k_p}\right)V_{IH} - V_{DD} - V_{T0,p}$$

$$V_{IH} = \frac{V_{DD} + V_{T0,p} + K_R(2V_{out} + V_{T0,n})}{1 + K_R}$$

Static Loss

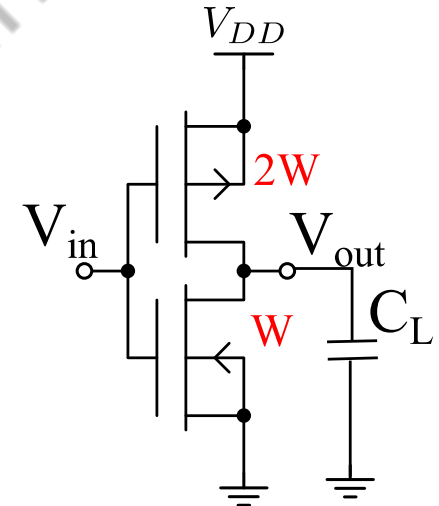
➤ Causes for High Static Power Consumption

Effect of Decreasing V_{DD} on Delay

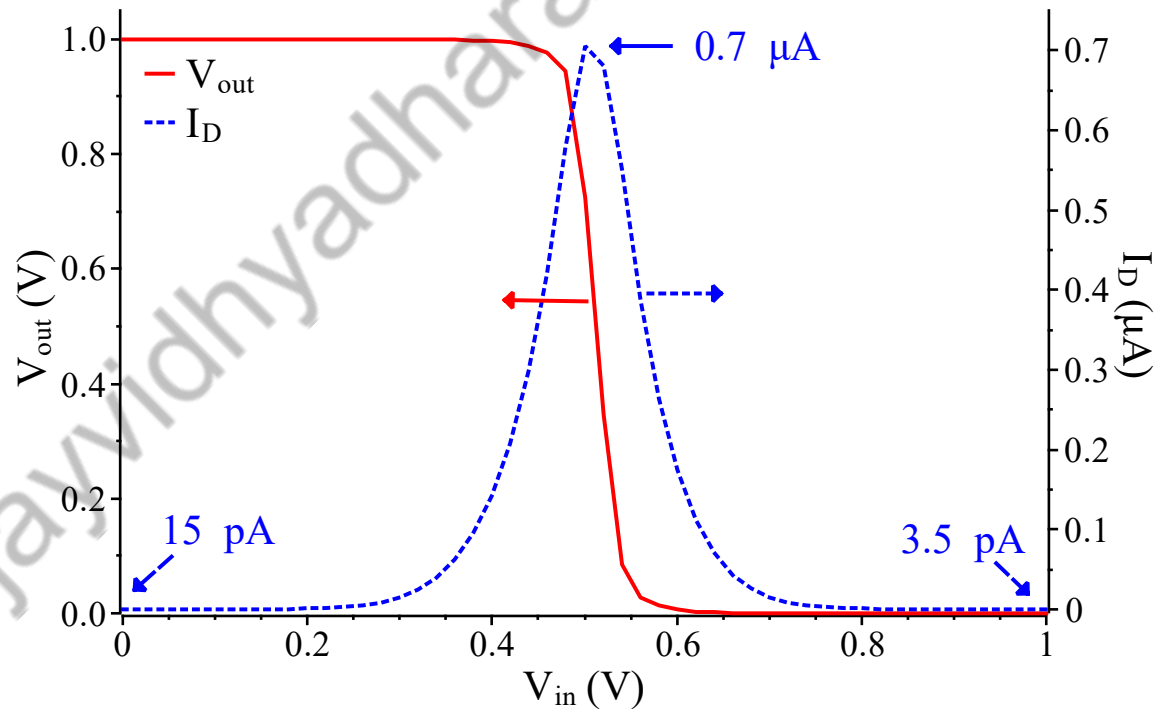
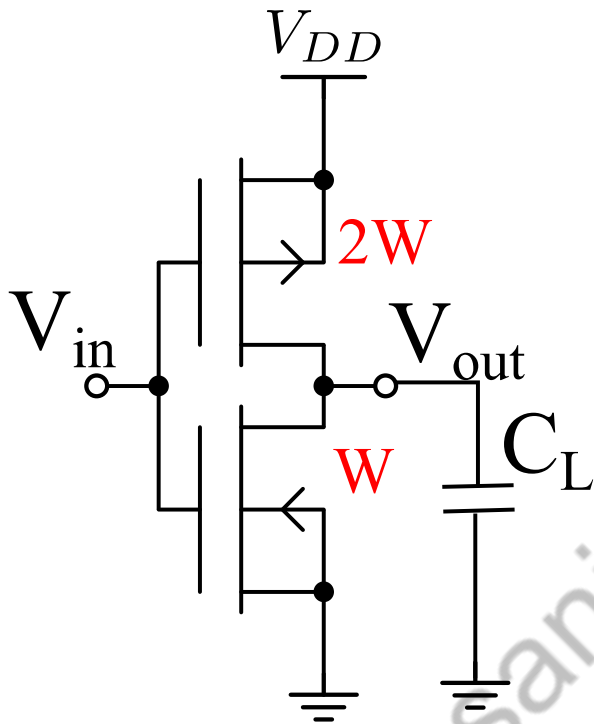
$$\text{Propagation Delay } (t_{pd}) = \frac{K_1 C_L}{I_D} = \frac{K_2 C_L}{(V_{DD} - V_{th})^2}$$

Effect of Decreasing V_{th} on Power

- Intel estimated leakage power consumption at more than 50W for a 100nm technology node.
- Leakage depends strongly on a Threshold voltage (V_{th}) of the transistor



Static Loss



Static Loss

➤ Reducing Static Loss

- Device Level Techniques
 - Tunnel Field Effect Transistors
 - CNFETs
- Circuit Level Techniques when using CMOS

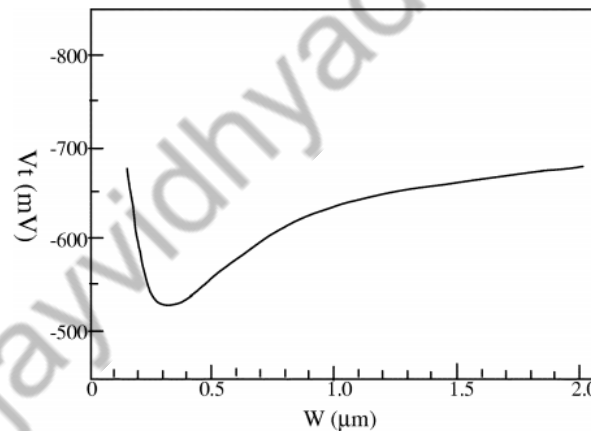


Fig. 12 Variation of threshold voltage with gate width in the case of trench isolated buried channel P-MOSFET showing the anomalous behavior [27].

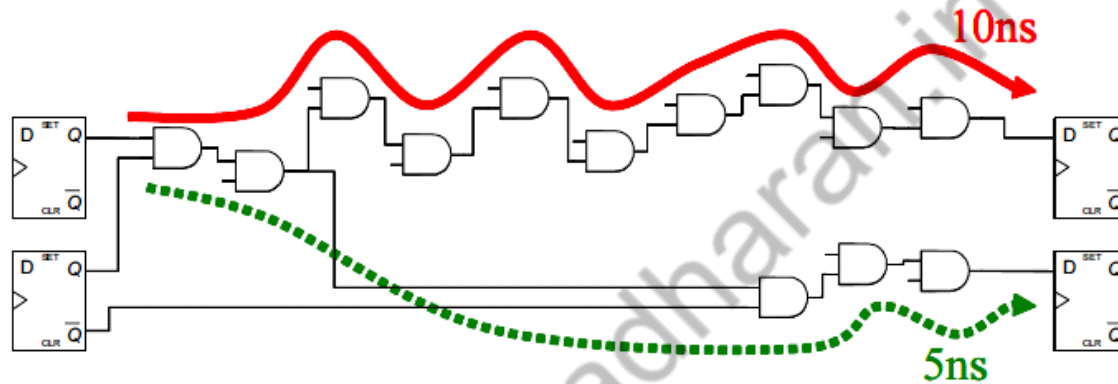
[3] K. Roy, S. Mukhopadhyay, and H. Mahmoodi-Meimand, "Leakage current mechanisms and leakage reduction techniques in deep-submicrometer CMOS circuits," Proceedings of the IEEE, vol. 91, no. 2, pp. 305–327, Feb. 2003.

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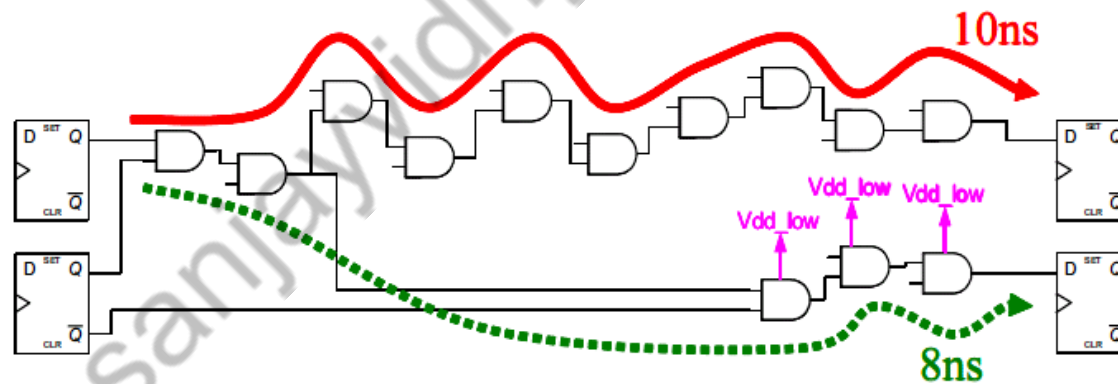
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Static Loss

Multiple V_{DD} for Power Reduction



Non-critical path may be delayed



Non-critical path runs with reduced supply voltage

- [5] M. Pedram and J.M. Rabaey, "Power aware design Methodologies," [Online]. Available: <https://www.springer.com/gp/book/9781402071522>

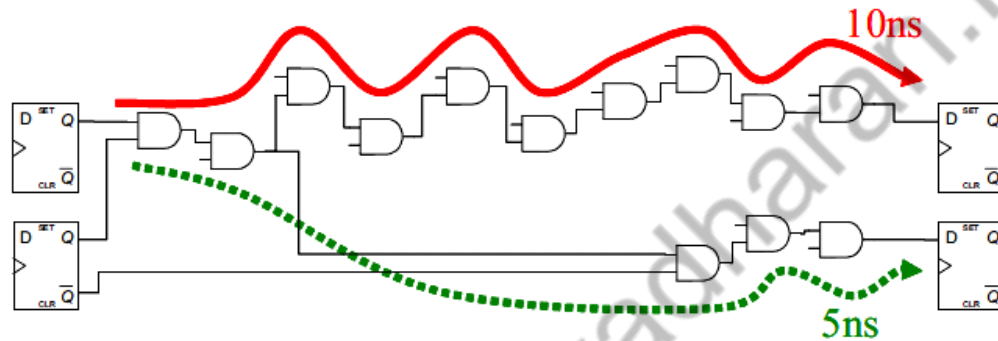
Static Loss

Challenges of Multi- V_{DD} Design

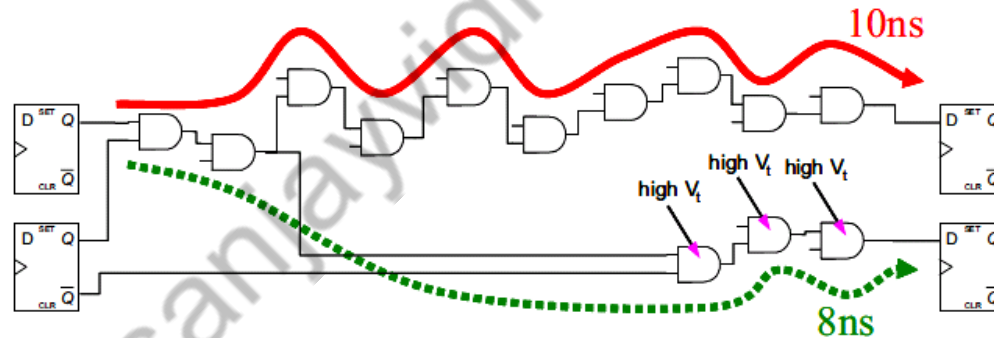
- The additional supply voltage V_{DD} needs to be created on-chip by a dc to dc converter.
- Area overhead, and in power consumption for the converter.
- Level-shifters are required between different supply domains.
- Multiple Routing

Static Loss

Multi- V_{th} Design



Non-critical path may be delayed



Non-critical path runs with increased threshold voltage

- [5] M. Pedram and J.M. Rabaey, "Power aware design Methodologies," [Online]. Available: <https://www.springer.com/gp/book/9781402071522>

Static Loss

Challenges of Multi- V_{th} Design

- **ADDITIONAL MASKS**
- **FOR EACH SUCH OPTION, THE DESIGN LIBRARY MUST BE ELECTRICALLY CHARACTERIZED, MODELED FOR ALL DESIGN TOOLS**

sanjayvidyadharan.in

Thank you